



June 1993
Revised March 1999

74LVX273 Low Voltage Octal D-Type Flip-Flop

General Description

The LVX273 has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset (MR) input load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the MR input. The

device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements. The inputs tolerate up to 7V allowing interface of 5V systems to 3V systems.

Features

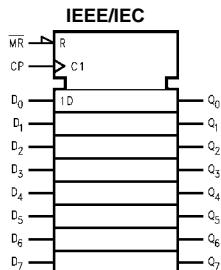
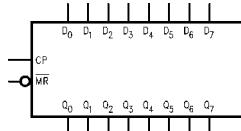
- Input voltage translation from 5V to 3V
- Ideal for low power/low noise 3.3V applications
- Guaranteed simultaneous switching noise level and dynamic threshold performance

Ordering Code:

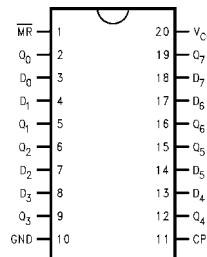
Order Number	Package Number	Package Description
74LVX273M	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LVX273SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVX273MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending letter suffix "X" to the ordering code.

Logic Symbols



Connection Diagram



Pin Descriptions

Pin Names	Description
D ₀ -D ₇	Data Inputs
MR	Master Reset
CP	Clock Pulse Input
Q ₀ -Q ₇	Data Outputs

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Truth Table

Operating Mode	Inputs			Outputs
	\overline{MR}	CP	D_n	
Reset ('1')	L	X	X	L
Load '1'	H	—	H	H
Load '0'	H	—	L	L

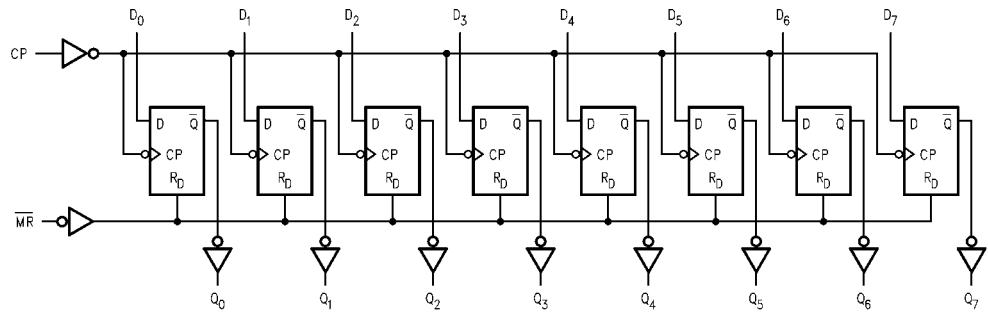
H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

— = LOW-to-HIGH Transition

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)			Recommended Operating Conditions (Note 2)				
Supply Voltage (V_{CC})	-0.5V to +7.0V		Supply Voltage (V_{CC})	2.0V to 3.6V			
DC Input Diode Current (I_{IK})			Input Voltage (V_I)	0V to 5.5V			
$V_I = -0.5V$	-20 mA		Output Voltage (V_O)	0V to V_{CC}			
DC Input Voltage (V_I)	-0.5V to 7V		Operating Temperature (T_A)	-40°C to +85°C			
DC Output Diode Current (I_{OK})			Input Rise and Fall Time ($\Delta t/\Delta V$)	0 ns/V to 100 ns/V			
$V_O = -0.5V$	-20 mA						
$V_O = V_{CC} + 0.5V$	+20 mA						
DC Output Voltage (V_O)	-0.5V to $V_{CC} + 0.5V$						
DC Output Source or Sink Current (I_O)		± 25 mA					
DC V_{CC} or Ground Current (I_{CC} or I_{GND})		± 75 mA					
Storage Temperature (T_{STG})	-65°C to +150°C						
Power Dissipation	180 mW						
DC Electrical Characteristics							
Symbol	Parameter	V_{CC}	$T_A = +25^\circ C$		$T_A = -40^\circ C$ to $+85^\circ C$	Units	Conditions
			Min	Typ	Max		
V_{IH}	HIGH Level Input Voltage	2.0	1.5		1.5		
		3.0	2.0		2.0		
V_{IL}	LOW Level Input Voltage	2.0		0.5	0.5		
		3.0		0.8	0.8		
V_{OH}	HIGH Level Output Voltage	2.0	1.9	2.0	1.9		
		3.0	2.9	3.0	2.9		
		3.0	2.58		2.48		
V_{OL}	LOW Level Output Voltage	2.0	0.0	0.1	0.1		
		3.0	0.0	0.1	0.1		
		3.0		0.36	0.44		
I_{OZ}	3-STATE Output Off-State Current	3.6		± 0.25	± 2.5	μA	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND
I_{IN}	Input Leakage Current	3.6		± 0.1	± 1.0	μA	$V_{IN} = 5.5V$ or GND
I_{CC}	Quiescent Supply Current	3.6		4.0	40.0	μA	$V_{IN} = V_{CC}$ or GND
Noise Characteristics (Note 3)							
Symbol	Parameter		V_{CC} (V)	$T_A = 25^\circ C$		Units	C_L (pF)
				Typ	Limit		
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}		3.3	0.5	0.8	V	50
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}		3.3	-0.5	-0.8	V	50
V_{IHD}	Minimum HIGH Level Dynamic Input Voltage		3.3		2.0	V	50
V_{ILD}	Maximum LOW Level Dynamic Input Voltage		3.3		0.8	V	50
Note 3: Input $t_r = t_f = 3ns$							

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AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = +25°C			T _A = -40°C to +85°C		Units	C _L (pF)
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay Time CP to Q _n	2.7		9.0	16.9	1.0	20.5	ns	15
				11.5	20.0	1.0	24.0		50
		3.3 ± 0.3		7.1	11.0	1.0	13.0		15
				9.6	14.5	1.0	16.5		50
t _{PHL}	Propagation Delay MR to Q _n	2.7		9.3	17.8	1.0	20.5	ns	15
				11.8	21.1	1.0	24.0		50
		3.3 ± 0.3		7.3	11.5	1.0	13.5		15
				9.8	15.0	1.0	17.0		50
t _S	Setup Time D _n to CP	2.7	8.0			9.5		ns	
		3.3 ± 0.3	5.5			6.5			
t _H	Hold Time D _n to CP	2.7	1.0			1.0		ns	
		3.3 ± 0.3	1.0			1.0			
t _{REC}	Removal Time MR to CP	2.7	4.0			4.0		ns	
		3.3 ± 0.3	2.5			2.5			
t _W	Clock Pulse Width	2.7	8.0			9.5		ns	
		3.3 ± 0.3	5.5			6.5			
t _W	MR Pulse Width	2.7	7.5			8.5		ns	
		3.3 ± 0.3	5.0			6.0			
f _{MAX}	Maximum Clock Frequency	2.7	55	110		45		MHz	15
			45	60		40			50
		3.3 ± 0.3	95	150		80			15
			60	90		50			50
t _{OSLH}	Output to Output Skew (Note 4)	2.7			1.5		1.5	ns	50
t _{OSHL}		3.3			1.5		1.5		

Note 4: Parameter guaranteed by design. t_{OSLH} = |t_{PLHm} - t_{PLHn}|, t_{OSHL} = |t_{PHLm} - t_{PHLn}|

Capacitance

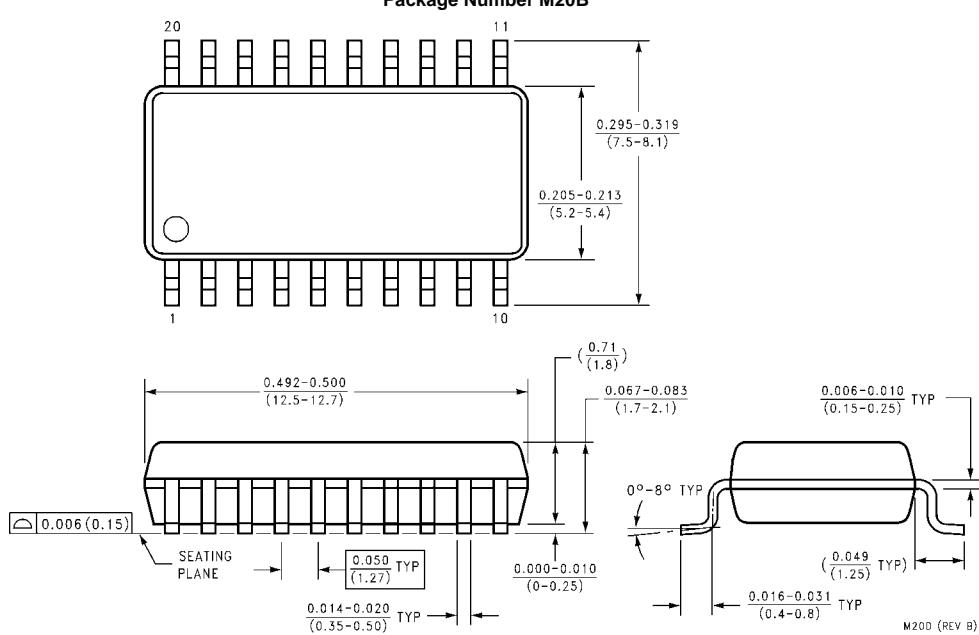
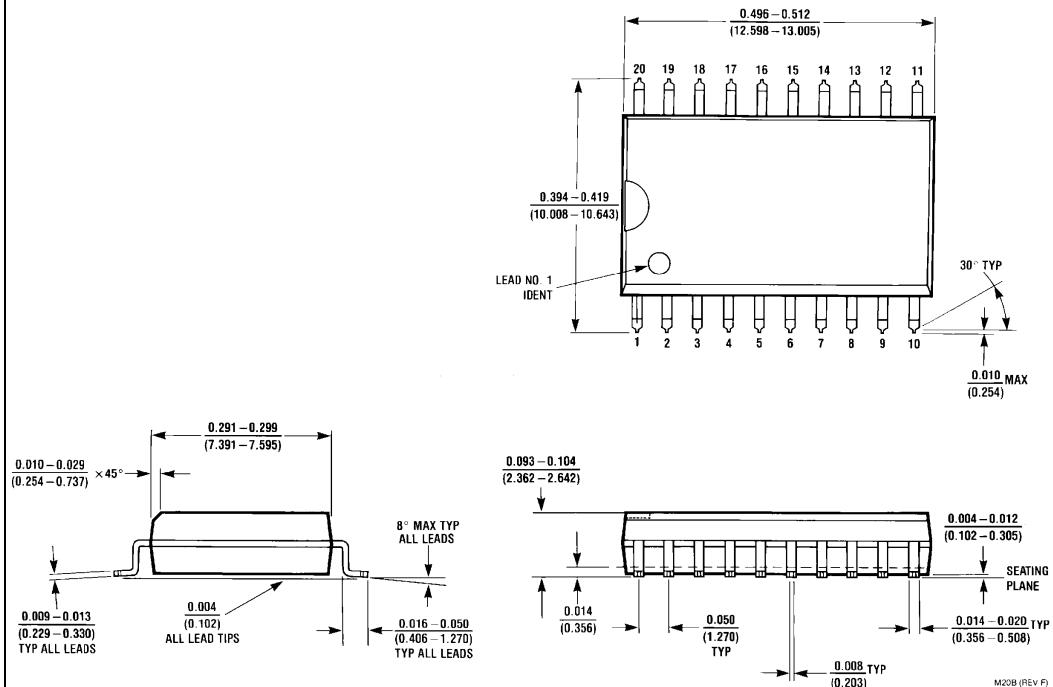
Symbol	Parameter	T _A = +25°C			T _A = -40°C to +85°C		Units	
		Min	Typ	Max	Min	Max		
C _{IN}	Input Capacitance			4	10		10	pF
C _{OUT}	Output Capacitance			6				pF
C _{PD}	Power Dissipation Capacitance (Note 5)			31				pF

Note 5: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

$$\text{Average operating current can be obtained by the equation: } I_{CC(\text{opr.})} = \frac{C_{PD} \times V_{CC} \times f_{IN} + I_{CC}}{8 \text{ (per F/F)}}$$

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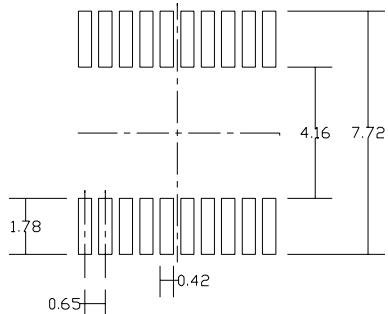
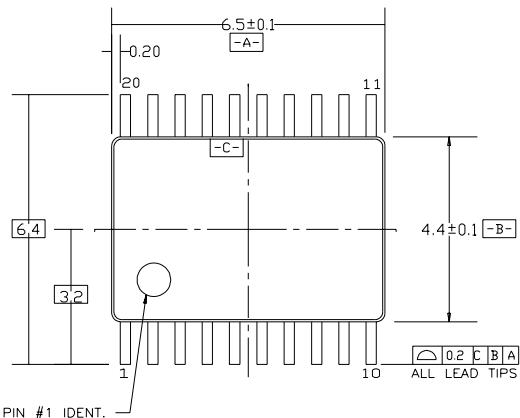
Physical Dimensions inches (millimeters) unless otherwise noted



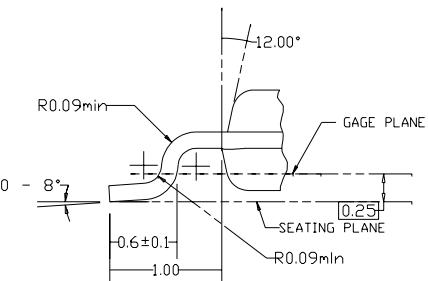
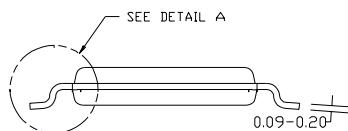
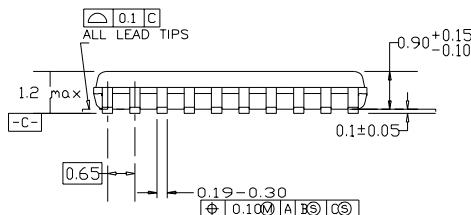
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74LVX273 Low Voltage Octal D-Type Flip-Flop

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DETAIL A

DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC,
REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH,
AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20**

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